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Press Release

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Boulder, CO – November 2, 2009 – Tech-X Corporation invites you to visit us at booth 637 at the [American Vacuum Society 56th International Symposium and Exhibition](#), November 8 - 13, 2009, in San Jose, CA..

Tech-X is proud to present the latest release of our electromagnetic plasma simulation software, [VORPAL](#). **For the first time, VORPAL 4.0 provides parallel and multi-core capability to the Windows platform** (as with previous versions, VORPAL 4.0 also runs in parallel on the Linux and Macintosh platforms). Let VORPAL 4.0 help you take full advantage of your multi-core desktop computer. Other new capabilities include:

- cylindrical coordinates for electromagnetic simulation
- automated eigenfrequency and eigenmode extraction from time-domain simulation
- new secondary electron models that allow simulations of complex metallic and dielectric boundaries of arbitrary shape without stairsteps
- improved post-processing, including automated import into the VisIt software for advanced visualization
- improved documentation, including a detailed, 180-page reference manual, a 160-page user guide, and a 157-page examples guide

Stop by our booth to see a demonstration of any of these new features of VORPAL 4.0. Our technical staff will be available at the booth and will be happy to discuss the details of how VORPAL might fit your modeling needs.

Sudhakar Mahalingham will be presenting a talk at the Exhibitor Workshop on Wednesday, November 11th at 1:20 PM on Modeling Electron Impact Collisions of Gas Mixtures Using Particle-in-Cell (PIC) Code, S. Mahalingam, S. Veitzer and P. Stoltz.